

Technical Committees

Computer-Aided Design

B PERLMAN

Co-chairman

S L MARCH

Submillimeter-Wave Techniques

K. J. BUTTON

Co-chairman

M AFSAR

Microwave and Millimeter-Wave Solid-State Devices

R. A. GILSON

Co-chairman

H. J. KUNO

Microwave Ferrites

J. M. OWENS

Co-chairmen

W. E. HORD
J. M. OWENS

Microwave Systems

J. B. HORTON

Microwave Network Theory

A. E. WILLIAMS

Microwave Acoustics

R. S. KAGIWADA

Microwave High-Power Techniques

J. GOEL

Co-chairman

N. WILSON

Biological Effects and Medical Applications

J. C. LIN

Microwave Low Noise Techniques

J. J. WHELEHAN, JR.
Co-chairman

K. AGARWAL

Digital Signal Processing

I. A. MACK

Fiber and Integrated Optics

Microwave and Millimeter-Wave Integrated Circuits

E. C. NIEHENKE

Microwave Measurements

S. F. ADAM

Microwave Field Theory

T. ITOH

Automatic RF Techniques

M. A. MAURY, JR.

Technical Committees Chairman

B. E. SPIELMAN

Co-chairman

H. J. KUNO

EDITORIAL BOARD

Editor

R. LEVY

H Abe	C Chao	P. F. Goldsmith	G Kantor	C. M. Miller	U. L. Rohde	G Thoren
M. Abouzahra	K. M. Chen	A. Gopinath	A. Karp	P. Miller	A. Rosen	J. C. Tippet
E. R. Adair	M. H. Chen	P. A. Goud	R. Kaul	J. Mink	F. J. Rosenbaum	C. Toker
J. D. Adam	W. C. Chew	V. I. Granatstein	S. Kawakami	T. Myoshi	S. W. Rosenthal	K. Tomiyasu
S. F. Adam	J. Y. Choe	P. Greiling	D. B. Keck	S. Mizushima	H. E. Rowe	R. Trambarulo
A. T. Adams	C.-K. Chou	E. J. Griffin	A. R. Kerr	A. H. Mohammadian	T. E. Rozzi	O. J. Tretiak
K. K. Agarwal	Y. L. Chow	V. Grigoriant	O. B. Kesler	C. R. Moore	C. T. Rucker	R. J. Trew
S. Ahn	K. R. Cioffi	R. W. Grow	P. J. Khan	R. A. Moore	D. Rutledge	T. N. Trick
M. Aikawa	M. Claassen	Q. Gu	D. D. Khandelwal	F. R. Morganthaler	D. Rytting	T. Trinh
M. Akaïke	P. J. Clarricoats	P. Guillon	B. Kim	N. Morita	A. A. M. Saleh	V. K. Tripathi
N. G. Alexopoulos	B. J. Clifton	T. Guldbrandsen	R. J. King	D. Y. Mouh	A. J. Sangster	W. C. Tsai
Y. Anand	E. D. Cohen	W. W. Guo	J. L. Kinzie	Y. Naito	E. W. Sard	G. N. Tsandoulas
K. Araki	M. Cohn	K. C. Gupta	M. Kisluk	N. Nakajima	T. K. Sarkar	H. Q. Tserng
F. Arndt	S. B. Cohn	M. S. Gupta	M. Klein	A. R. Nedunuri	R. Sato	C. Tsironis
A. E. Atia	P. D. Coleman	A. W. Guy	R. H. Knerr	D. P. Neikirk	R. H. Saul	M. Tsutsumi
H. A. Atwater	R. E. Collin	U. H. Gysel	J. B. Knorr	K. B. Niclas	G. Saulich	R. S. Tucker
N. F. Audeh	H. W. Cooper	G. I. Haddad	M. Kobayashi	W. C. Niehaus	J. O. Scanlan	A. Uhlir
B. A. Auld	N. W. Cox	M. J. Hagmann	Y. Kobayashi	J. Nishizawa	J. Schaefer	B. Ulriksson
I. Awaï	M. L. Crawford	B. R. Hallford	T. Koike	J. D. Nordgard	D. H. Schaubert	L. C. Upadhyayula
Y. Ayashi	E. G. Cristal	M. A. K. Hamid	J. Komiak	G. Novick	J. M. Schellenberg	P. L. E. Uslenghi
I. J. Bahl	H. M. Cronson	R. C. Hansen	J. A. Kong	G. H. Nussbaum	W. O. Schlosser	J. Van Bladel
A. J. Bahr	T. W. Crowe	R. F. Harrington	Y. Konishi	D. P. Nyquist	L. P. Schmidt	R. L. Van Tuyl
J. W. Bandler	A. L. Cullen	C. Hartman	A. Konrad	H. Ogawa	M. V. Schneider	P. M. van den Berg
F. S. Barnes	W. R. Curtice	H. L. Hartnagel	N. S. Kopeika	K. Ogusu	H. E. Schrank	A. Vander Vorst
J. Barrera	W. E. Dahlke	H. Hasegawa	H. G. Kosmahl	Y. Okabe	K. F. Schunemann	A. van der Ziel
P. P. Barsony	P. Daly	M. Hashimoto	E. Kraemer	F. Okada	S. R. Seshadri	J. Vorhaus
H. Bassen	J. B. Davies	R. E. Hayes	M. K. Krage	H. Okamoto	J. C. Sethares	W. A. G. Voss
T. E. Batchman	L. E. Davis	R. M. Healy	J. G. Kretzschmar	H. C. Okean	A. K. Sharma	D. F. Wait
B. Bates	J. E. Degenford	G. L. Heiter	C. M. Krowne	T. Okoshi	H. Shibata	R. A. Waldron
R. H. T. Bates	H. deGruyl	J. Helszajn	B. B. Ktaroglu	S. Okwit	H. Shigesawa	R. N. Wallace
H. C. Bell	E. J. Denlinger	S. J. Hewitt	W. Ku	W. W. Oldfield	Y. C. Shih	J. Walsh
E. Belohoubek	F. C. de Ronde	R. G. Hicks	E. F. Kuester	A. A. Oliner	T. Shiozawa	L. Wandering
P. Bernardi	G. A. Deschamps	A. Higashisaka	M. Kumar	H. G. Oltman	K. Shirahata	J. J. H. Wang
F. Bernues	S. Dixon	D. A. Hill	H. J. Kuno	A. S. Omar	T. Shishido	J. Watson
H. L. Bertoni	C. Dragone	M. E. Hines	R. Kuvas	J. Ondria	J. Shmoys	N. G. Watson
A. Beyer	C. H. Durney	K. Hirai	P. M. La Tourrette	K. Osafune	P. W. Shumate	D. Webb
J. B. Beyer	M. Dydyk	W. J. R. Hoefer	L. E. Larsen	J. M. Osepchuk	P. H. Siegel	J. Webb
P. Bhartia	J. Edrich	C. A. Hoer	C. H. Lee	T. Y. Otoshi	P. Silvester	W. T. Weeks
M. E. Bialkowski	R. Eisenhart	R. K. Hoffmann	C. S. Lee	J. M. Owens	G. Smith	S. Weinreb
T. A. Bickart	G. Eisenstein	D. C. Hogg	K. J. Lee	R. W. Paglione	A. W. Snyder	J. A. Weiss
D. M. Bolle	M. El-Sherbiny	C. H. Holmes	M. C. Lee	S. F. Paik	R. V. Snyder	F. S. Welsh
C. R. Boyd	R. S. Elliott	W. E. Hord	S. W. Lee	D. Parker	H. Sobol	S. H. Wemple
J. A. Bradshaw	R. Engelmann	D. Hornbuckle	Y. Levitan	C. Pask	K. Solbach	C. P. Wen
W. B. Bridges	G. F. Engen	J. B. Horton	R. Levy	J. A. Pearce	P. I. Somlo	R. J. Wenzel
M. F. Brodwin	W. J. English	M. C. Horton	J. C. Lin	J. Perini	R. Sorrentino	R. G. West
D. M. Brookbanks	G. W. Ewell	H. Howe	I. V. Lindell	B. S. Perlman	R. A. Sparks	J. J. Whelehan
G. H. Brooke	M. Faber	H. P. Hsu	H. Ling	S. M. Perlow	R. A. Speciale	L. R. Whicker
L. Bui	N. H. Farhat	C. P. Hu	J. D. Love	W. C. Petersen	B. E. Spielman	J. F. White
C. Buntschuh	S. J. Fiedzusko	C. C. Huang	N. Luhman	D. F. Peterson	P. J. Stabile	A. E. Williams
C. M. Butler	R. E. Fisher	H. Ikuno	T. Lukaszek	G. E. Peterson	P. Staecker	A. G. Williamson
J. Butler	V. A. Flyagin	W. J. Ince	S. A. Maas	R. M. Phillips	R. B. Stanciliff	R. W. Wilson
K. J. Button	T. Fong	M. F. Iskander	D. Maki	J. Pierro	W. H. Steier	D. R. Wilton
J. A. Calviello	K. R. Foster	T. Itoh	M. Makimoto	R. D. Pollard	K. D. Stephan	J. C. Wiltse
R. L. Camisa	G. Franceschetti	F. Ivanek	M. Malkomes	M. Pospieszalski	R. A. Stern	W. Wisselman
J. Campbell	E. Freibergs	D. Jablonski	S. L. March	R. Pregia	F. Sterzer	I. Wolff
A. G. Cardasmenos	H. Fukui	D. Jager	D. Masse	A. C. Priou	H. E. Stinehelfer	G. T. Wrixon
H. J. Carlin	Y. Fukuoka	R. H. Jansen	R. Matthauch	R. A. Pucel	S. S. Stuchly	Y.-S. Wu
E. R. Carlson	G. J. Gabriel	A. Jelenksi	G. L. Matthaui	J. L. Putz	C. Sun	S. Yamamoto
P. H. Carr	R. J. Gagne	G. Jerinic	P. Mayes	J. P. Quine	M. Suzuki	E. Yamasaki
J. Carroll	Z. Galani	R. Jesch	S. R. Mazumder	J. Raue	W. Tabbara	H. Yamashita
Z. J. Cendes	H. Gamo	P. B. Johns	N. A. McDonald	C. Rauscher	A. Taflove	K. Yashiro
D. Ch'en	O. P. Gandhi	D. S. Jones	T. F. McMaster	M. E. Read	C. T. Tai	K. Yasuura
R. J. Chaffin	Y. Garault	A. K. Jordan	M. W. Medley	T. M. Reeder	Y. Tajima	C. W. H. Yeh
C. S. Chang	F. E. Gardiol	H. R. Jory	K. K. Mei	C.-L. Ren	Y. Takayama	H. C. Yen
C. T. M. Chang	R. V. Garver	J. S. Joshi	P. J. Meier	P. L. Richards	S. H. Talisa	G. L. Yip
D. C. Chang	L. E. Gatterer	R. Kagiwada	H. Meinel	A. N. Riddle	T. Tamir	T. Yoneyama
K. Chang	V. G. Gelnovatch	D. Kajfez	W. Menzel	E. Rivier	J. Taub	T. Yukawa
S. K. Chang	W. J. Getsinger	M. Kanda	K. A. Michalski	D. A. Rogers	R. Terakado	K. A. Zaki
W. S. C. Chang						

INFORMATION FOR AUTHORS

IEEE TRANSACTIONS ON MICROWAVE THEORY AND TECHNIQUES is published monthly. Manuscripts should be prepared especially for publication in this TRANSACTIONS and submitted to the Editor, Ralph Levy, KW Engineering, 4565 Ruffner Street, San Diego, CA 92111. The manuscripts must be typed double-spaced on 22×28 cm ($8\frac{1}{2} \times 11$ in) sheets. Four copies of both the manuscript and accompanying illustrations should be submitted. A list of illustrations should be included in each copy of the manuscript. Original illustrations should not be submitted initially. They will be called for if the paper is accepted for publication. Also, an author whose manuscript is accepted as a PAPER (but not as a SHORT PAPER) is requested to submit a short biography and a clear, glossy portrait upon acceptance. Each manuscript must include an abstract of not more than 200 words and the complete address of the corresponding author. The Editor reserves the right to return without a review manuscripts exceeding approximately 20 double-spaced typewritten pages plus 20 figures. SHORT PAPERS are limited to three pages of the TRANSACTIONS, and should describe new research results or modifications to those already published in the literature. For guidance, one TRANSACTIONS page is equivalent to four doubly-spaced typewritten pages or to four figures. LETTERS are generally limited to comments and replies to material previously published in this TRANSACTIONS, suggestions for new work, errata, and other exceptionally short articles. "Information for IEEE authors" is available upon request from the IEEE Publications Department, 345 East 47th Street, New York, NY 10017.

Copyright

It is the policy of the IEEE to own the copyright to the technical contributions it publishes on behalf of the interest of the IEEE, its authors, and their employers, and to facilitate the appropriate reuse of this material by others. To comply with the U.S. Copyright Law, authors are required to sign an IEEE Copyright Form before publication. This form, a copy of which appears in each January issue of this TRANSACTIONS, returns to authors and their employers full rights to reuse their material for their own purposes. Authors must submit a signed copy of this form with their manuscripts.

Clearance of Manuscripts

The IEEE must of necessity assume that materials presented at its meetings or submitted to its publications are properly available for general dissemination to the audiences these activities are organized to serve. It is the responsibility of the author, not the IEEE, to determine whether disclosure of their material requires the prior consent of other parties, and if so, to obtain it.

Publication Policy

Papers will be reviewed for their technical merit, and decisions to publish will be made independently of an author's ability or willingness to pay page charges. *Voluntary page charges* of \$110 per printed page will be requested for papers of five pages or less. Page charges of \$110 per page are mandatory for each page in excess of five printed pages. Also, the MTT-S Administrative Committee has established a quota for the number of pages printed in each issue of this TRANSACTIONS whose costs are not defrayed by payment of page charges. Papers not covered by page charges may be delayed until space in an issue is available. The Editor can waive the quota requirement for exceptional papers or because of other extenuating circumstances.